

HEXFRED® Ultrafast Soft Recovery Diode, 70 A



PRIMARY CHARACTERISTICS				
V _R	1200 V			
V _F (typical)	2.3 V			
t _{rr} (typical)	51 ns			
I _{F(AV)} per module at T _C	70 A at 94 °C			
Package	SOT-227			

FEATURES

- · Fast recovery time characteristic
- · Electrically isolated base plate
- Large creepage distance between terminal
- · Simplified mechanical designs, rapid assembly
- · Designed and qualified for industrial level
- UL approved file E78996



• Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

DESCRIPTION / APPLICATIONS

The dual diode series configuration (VS-HFA70FA120) is used for output rectification or freewheeling/clamping operation and high voltage application.

The semiconductor in the SOT-227 package is isolated from the copper base plate, allowing for common heatsinks and compact assemblies to be built.

These modules are intended for general applications such as HV power supplies, electronic welders, motor control and inverters.

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS	
Cathode to anode voltage	V _R		1200	V	
Continuous forward current per leg	I _F	T _C = 110 °C	35	۸	
Single pulse forward current per leg	I _{FSM}	T _J = 25 °C	380	Α	
Maximum power dissipation per module	P _D	T _C = 110 °C	174	W	
RMS isolation voltage	V _{ISOL}	Any terminal to case, t = 1 min	2500	V	
Operating junction and storage temperature range	T _J , T _{Stg}		-55 to +150	°C	

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V_{BR}	I _R = 100 μA	1200	-	-	
For each allows		I _F = 30 A	-	2.30	3.00	.,
	Forward voltage V _{FM}	I _F = 60 A	-	2.89	3.80	V
Forward voltage		I _F = 30 A, T _J = 125 °C	-	2.14	2.44	
		I _F = 60 A, T _J = 125 °C	-	2.82	3.27	
		$V_R = V_R$ rated	-	1.2	75	μΑ
Reverse leakage current	I _{RM}	T _J = 125 °C, V _R = V _R rated	-	1.0	-	mA
		$T_J = 150 ^{\circ}\text{C}, V_R = V_R \text{rated}$	-	2.7	10] IIIA



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
		$I_F = 1 A; dI_F/d$	$t = 200 \text{ A/}\mu\text{s}; V_R = 30 \text{ V}$	-	51	-	
Reverse recovery time	t _{rr}	T _J = 25 °C		-	134	-	ns
		T _J = 125 °C		-	204	-	
Dook receivery ourrent		T _J = 25 °C	$I_F = 50 \text{ A}$	-	12	-	Α
Peak recovery current	I _{RRM}	T _J = 125 °C	$dI_F/dt = -200 A/\mu s$ $V_R = 200 V$	-	18	-	A
Reverse recovery charge Q _{rr}	T _J = 25 °C	''	-	790	-	nC	
	Q _{rr}	T _J = 125 °C		-	1770	-	IIC
Junction capacitance	C _T	V _R = 1200 V		-	24	-	pF

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Junction to case, single leg conducting	D		-	-	0.46	
Junction to case, both legs conducting	R _{thJC}		-	-	0.23	°C/W
Case to heatsink	R _{thCS}	Flat, greased surface	-	0.10	-	
Weight			-	30	-	g
Mounting torque		Torque to terminal	-	-	1.1 (9.7)	Nm (lbf.in)
Mounting torque		Torque to heatsink	-	-	1.8 (15.9)	Nm (lbf.in)
Case style			SOT-227			

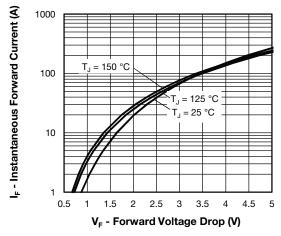


Fig. 1 - Typical Forward Voltage Drop Characteristics (Per Leg)

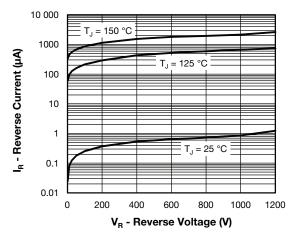


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

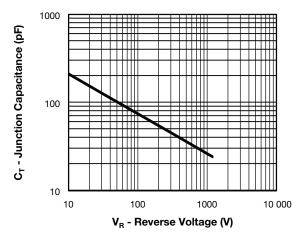


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

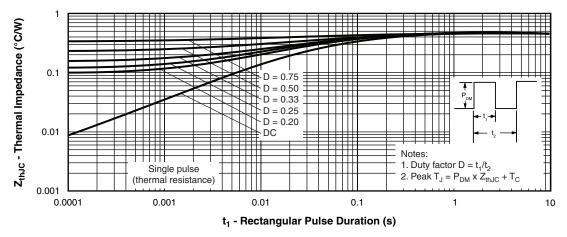


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)

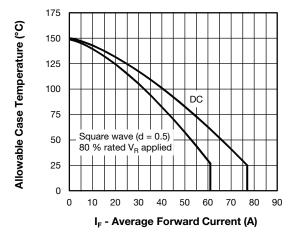


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current (Per Leg)

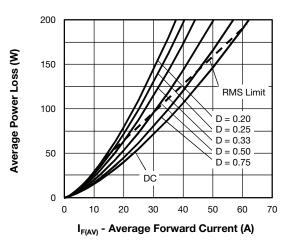
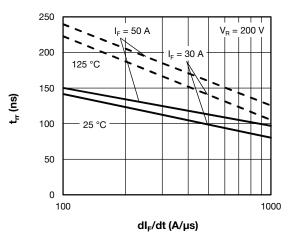


Fig. 6 - Forward Power Losses Characteristics (Per Leg)





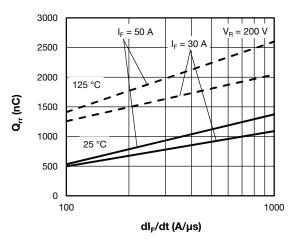


Fig. 8 - Typical Stored Charge vs. dl_F/dt

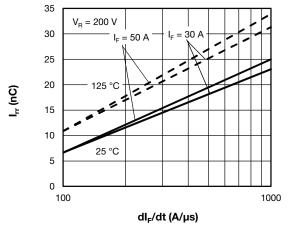


Fig. 9 - Typical Reverse Recovery Current vs. dl_F/dt

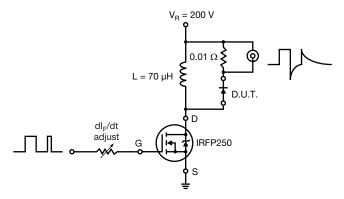
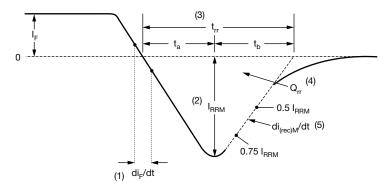


Fig. 10 - Reverse Recovery Parameter Test Circuit

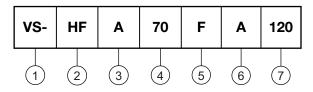


- (1) di_F/dt rate of change of current through zero crossing
- (4) \mathbf{Q}_{rr} area under curve defined by \mathbf{t}_{rr} and \mathbf{I}_{RRM}
- (2) I_{RRM} peak reverse recovery current
- $Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RBM} and 0.50 I_{RBM} extrapolated to zero current.
- (5) $di_{(rec)M}/dt$ peak rate of change of current during $t_{\rm b}$ portion of $t_{\rm rr}$

Fig. 11 - Reverse Recovery Waveform and Definitions

ORDERING INFORMATION TABLE

Device code



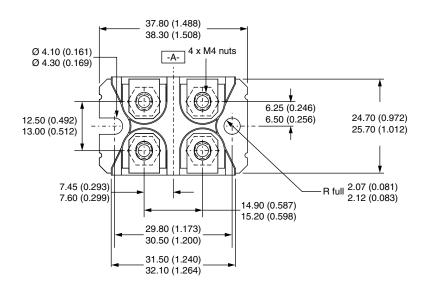
- Vishay Semiconductors product
- 2 HEXFRED® family
- Process designator (A = electron irradiated)
- 4 Current rating (70 = 70 A)
- 5 Circuit configuration (two separate diodes, parallel pin-out)
- Package indicator (SOT-227 standard insulated base)
- 7 Voltage rating (120 = 1200 V)

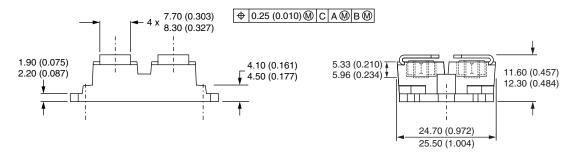
CIRCUIT CONFIGURATION						
CIRCUIT	CIRCUIT CONFIGURATION CODE	CIRCUIT DRAWING				
Two separate diodes, parallel pin-out	F	Lead Assignment 4 0 0 3 4 1 0 0 2 1				

LINKS TO RELATED DOCUMENTS					
Dimensions	www.vishay.com/doc?95423				
Packaging information	www.vishay.com/doc?95425				

SOT-227 Generation 2

DIMENSIONS in millimeters (inches)





Note

· Controlling dimension: millimeter



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Vishay

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